

REMARKS

The above amendments to the above-captioned application along with the following remarks are being submitted as a full and complete response to the Official Action dated August 11, 2005 (Paper No. 20050806). In view of the above amendments and the following remarks, the Examiner is respectfully requested to give due reconsideration to this application, to indicate the allowability of the claims, and to pass this case to issue.

On July 13, 2004 a certified copy of the corresponding priority document, Japanese patent application 2003-187377, claiming the priority date of June 30, 2003, was filed in the U.S. Patent and Trademark Office. Acknowledgement of receipt of the certified copy of the corresponding priority document is respectfully requested.

Status of the Claims

Claims 1 through 16 are currently pending in the above-identified application. Claims 17 through 37 have been previously cancelled without prejudice or disclaimer of their subject matter. Also, Claims 1, 3, 4, 8, 9, 11 and 15 are being amended to correct formal errors, place the claims in better form and to more particularly point out and distinctly claim the subject invention. Entry of the amendments to Claims 1, 3, 4, 8, 9, 11 and 15 is respectfully requested.

Additional Amendments

The Specification and the Abstract of the Disclosure have been amended and previously set forth herein. Entry of the amendments to the Specification and the Abstract of the Disclosure is respectfully requested.

In Figure 21 of the drawings the letter "m" and the corresponding lead line have been added. In Figures 23 and 24 of the Drawings, the legend "Conventional Art" has been added. Also, in Figures 25 and 26 of the drawings the legend "Related Art" has been added. Entry of these drawing corrections is respectfully requested.

Formal Objection

Figures 23 through 26 were objected to in that they should be designated by an appropriate legend. In response, in Figures 23 and 24 of the Drawings, the legend "Conventional Art" has been added. Also, in Figures 25 and 26 of the drawings the legend "Related Art" has been added. Withdrawal of the objection to the Figures 23 through 26 of

the drawings is respectfully requested.

Prior Art Rejections

Claims 1 through 10 and 14 through 16 were rejected under 35 U.S.C. § 102(b) over U.S. Patent No. 6,307,272 to Takahashi et al., hereinafter the Takahashi '272 patent. This rejection is respectfully traversed.

Claims 11 through 13 were rejected under 35 U.S.C. § 103(a) over the Takahashi '272 patent in view of U.S. Patent Application Publication No. 2003/0062608 to Hamachi, hereinafter the Hamachi '608 application. This rejection is respectfully traversed.

It is respectfully submitted that the Takahashi '272 patent and the Hamachi '608 application do not disclose:

a semiconductor device, wherein the control electrode pad is arranged at a position from the control electrode lead and the second electrode lead farther than the second electrode pad, wherein the control electrode pad has a first side which is most close to the control electrode lead and the second electrode lead, wherein the second electrode pad has a second side which is most far from the control electrode lead and the second electrode lead, and wherein the first side of the control electrode pad is located at a position from the control electrode lead and the second electrode lead farther than the second side of the second electrode pad, as respectively recited in independent Claim 1.

In a semiconductor device of the present invention, such as recited in Claim 1, the gate electrode pad 12 is arranged at a position from the control electrode lead 6 and the second electrode lead 5 farther than the second electrode pad, such as the source electrode pad 11.

In such a semiconductor device of the present invention, the possibility that a bonding tool is brought into contact with the lead post, such as lead post 6a, is minimized. Therefore, it is respectfully submitted that, in the present invention, performance of reliable wire bonding is promoted.

As to the Takahashi '272 patent, the position of the Examiner that the Takahashi '272 patent "shows a semiconductor device . . . wherein the control electrode pad is arranged at a position from the control electrode lead and the second electrode lead farther than the second electrode pad. . . ", the Office Action referring to Figure 1 of the Takahashi '272 patent, (Office Action, page 3) is respectfully traversed.

In contrast, referring to Figure 10 of the Takahashi '272 patent, Figure 10 therein

illustrates a part of the lead frame after wire bonding in a semiconductor device of a first embodiment therein, with Figure 1 therein also illustrating such first embodiment of the Takahashi '272 patent. (Col. 10, lines 26-53 of the Takahashi '272 patent). As is shown in Figure 10 of the Takahashi '272 patent, the gate electrode 12 is not illustrated as being arranged at a position from the wire pad 43 and coupling portion 20 farther than the source electrode 11. (See also Col. 17, lines 33-48 of the Takahashi '272 patent).

Therefore, it is respectfully submitted that the Takahashi '272 patent does not disclose a semiconductor device, wherein the control electrode pad is arranged at a position from the control electrode lead and the second electrode lead farther than the second electrode pad, wherein the control electrode pad has a first side which is most close to the control electrode lead and the second electrode lead, wherein the second electrode pad has a second side which is most far from the control electrode lead and the second electrode lead, and wherein the first side of the control electrode pad is located at a position from the control electrode lead and the second electrode lead farther than the second side of the second electrode pad, as respectively recited in independent Claim 1.

As to the Hamachi '608 application, the Hamachi '608 application was only cited for its disclosure of a connecting means formed of a conductive plate, as to dependent Claim 11, and, as to dependent Claims 12 and 13, the Takahashi '272 patent in view of the Hamachi '608 application was cited for the disclosure of a second electrode pad and the second electrode lead connected by an adhesive material. However, the Office Action also stated, as to dependent Claims 12 and 13, that the Takahashi '272 patent in view of the Hamachi '608 application does not disclose the conductive plate being formed of a resilient ribbon strap and connected by ultrasonic wave bonding or formed of a metal plate molded in a predetermined shape. (Office Action pages 7 and 8). Further, it is respectfully submitted that the Hamachi '608 application was not cited for disclosing "... a semiconductor device ... wherein the control electrode pad is arranged at a position from the control electrode lead and the second electrode lead farther than the second electrode pad. ...".

Therefore, in view of the foregoing, it is respectfully submitted that independent Claim 1 is not anticipated by the Takahashi '272 patent; and Claims 11 through 13, which ultimately depend from Claim 1, are not obvious over the Takahashi '272 patent in view of the Hamachi '608 application. Also, Claims 2 through 10 and 14 through 16, which ultimately depend from Claim 1, are at least allowable for the same reasons that Claim 1 is allowable.

Therefore, withdrawal of the 35 U.S.C. § 102(b) rejection of Claims 1 through 10 and 14 through 16 and withdrawal of the 35 U.S.C. § 103(a) rejection of Claims 11 through 13 are respectfully requested.

Reconsideration and allowance of Claims 1 through 16 are respectfully requested.

Conclusion

In view of all the above, Applicants respectfully submit that certain clear and distinct differences as discussed exist between the present invention as now claimed and the prior art references upon which the rejections in the Office Action rely. These differences are more than sufficient that the present invention as now claimed would not have been anticipated nor rendered obvious given the prior art. Rather, the present invention as a whole is distinguishable, and thereby allowable over the prior art.

Favorable reconsideration of this application as amended is respectfully solicited. Should there be any outstanding issues requiring discussion that would further the prosecution and allowance of the above-captioned application, the Examiner is invited to contact the Applicants' undersigned representative at the address and telephone number indicated below.

Respectfully submitted,

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IN THE DRAWINGS:

In Figure 21 of the drawings the letter “m” and the corresponding lead line have been added. In Figures 23 and 24 of the Drawings, the legend “Conventional Art” has been added. Also, in Figures 25 and 26 of the drawings the legend “Related Art” has been added. Submitted concurrently herewith is a Letter to the Office Draftsperson and accompanying replacement drawing sheets for Figures 21 and 23 through 26 including the above identified corrections. Entry of these drawing corrections is respectfully requested.